

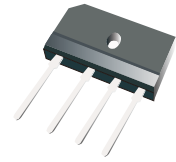
GBJ2506-HF Thru. GBJ2510-HF

Reverse Voltage: 600 to 1000V

Forward Current: 25.0A

RoHS Device

Halogen Free

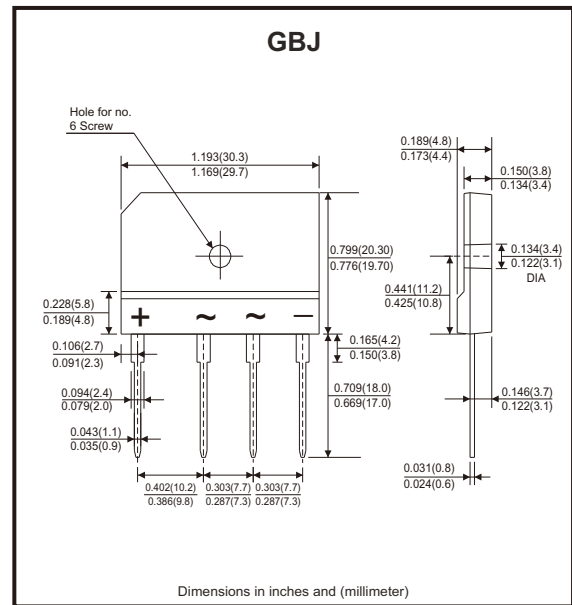


Features

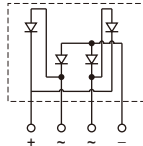
- Thin single in-line package.
- High surge current capability.
- Solder dip 275°C max. 7s, per JESD 22-B106.
- UL recognized file # E349301

Mechanical Data

- Case: Molded plastic, GBJ
- Epoxy: UL 94V-0 rate flame retardant.
- Polarity: As marked on body.
- Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102.



Circuit Diagram



Maximum Ratings and Electrical Characteristics (at Ta=25°C unless otherwise specified)

Parameter	Symbol	GBJ2506-HF	GBJ2508-HF	GBJ2510-HF	Unit
Maximum recurrent peak reverse voltage	V_{RRM}	600	800	1000	V
Average rectified output current @60Hz sine wave, R-load	I_O	25.0		1000	A
With heatsink Tc=87°C		25.0			
Without heatsink Ta=25°C	3.5				
Surge (non-repetitive) forward current @60Hz half sine wave, 1 cycle, Tj=25°C	I_{FSM}	350			A
Current squared time @ 1ms ≤ t ≤ 8.3ms Tj=25°C, rating of per diode	I^2t	508			A ² s
Maximum instantaneous forward voltage drop per diode	$I_{FM}=12.5A$ V_F	1			V
Maximum DC reverse current at rated DC blocking voltage per diode	$V_{RM}=V_{RRM}$ I_{RRM}	5			μA
Junction temperature range	T_J	-55 to +150			°C
Storage temperature range	T_{STG}	-55 to +150			°C
Dielectric strength @ terminals to case, AC 1 minute	V_{dis}	2.5			KV
Mounting torque @ recommend torque: 5kg.cm	T_{or}	8			kg.cm
Thermal resistance	Between junction and ambient, without heatsink	$R_{θJA}$	22		°C/W
	Between junction and case, with heatsink	$R_{θJC}$	1.0		°C/W

Rating and Characteristics Curves (GBJ2506-HF Thru. GBJ2510-HF)

Fig.1 - I_o — T_c Curve

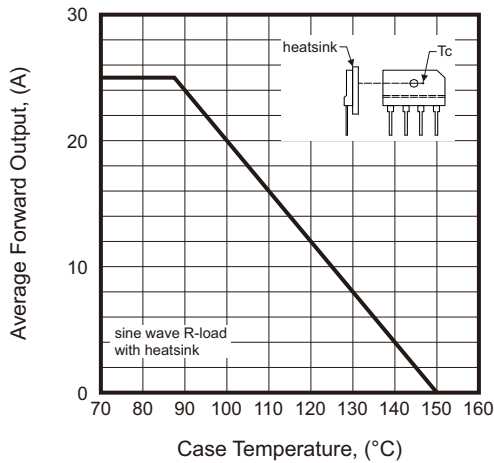


Fig.2 - Surge Forward Current Capability

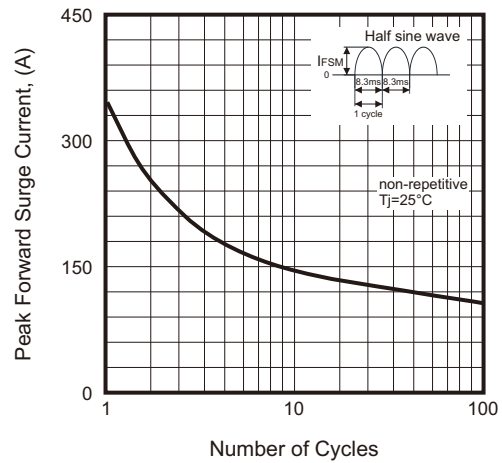


Fig.3 - Forward Voltage

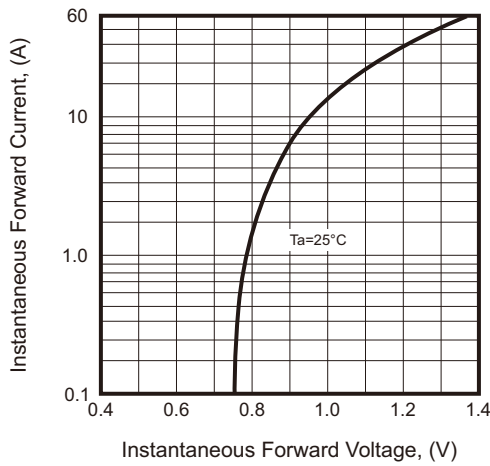


Fig.4 - Typical Reverse Characteristics

